



capability will enable the designer to interface any TTL family to CMOS. The availability of the base lead allows optimized gain/bandwidth adjustment in analog applications. The shallow depth of the IC photodiode provides better radiation immunity than conventional phototransistor couplers.

These products are also available with the transistor base node connected to improve common mode noise immunity and ESD susceptibility. In addition, higher CTR minimums are available by special request.

Package styles for these parts are 8 and 16 pin DIP through hole (case outlines P and E respectively), 16 pin DIP flat pack (case outline F), and leadless ceramic chip carrier (case outline 2).

Devices may be purchased with a variety of lead bend and plating options, see Selection Guide Table for details. Standard Military Drawing (SMD) parts are available for each package and lead style.

Because the same functional die (emitters and detectors) are used for each channel of each device

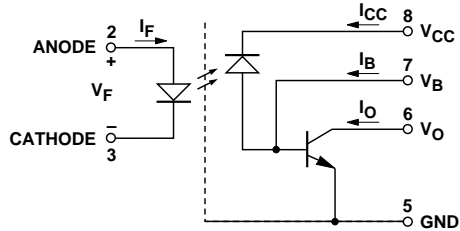
listed in this data sheet, absolute maximum ratings, recommended operating conditions, electrical specifications, and performance characteristics shown in the figures are identical for all parts. Occasional exceptions exist due to package variations and limitations and are as noted. Additionally, the same package assembly processes and materials are used in all devices. These similarities give justification for the use of data obtained from one part to represent other part's performance for die related reliability and certain limited radiation test results.

### Selection Guide—Package Styles and Lead Configuration Options

Package	16 Pin DIP	8 Pin DIP	8 Pin DIP	16 Pin Flat Pack	20 Pad LCCC
Lead Style	Through Hole	Through Hole	Through Hole	Unformed Leads	Surface Mount
Channels	2	1	2	4	2
Common Channel Wiring	None	None	V <sub>CC</sub> GND	V <sub>CC</sub> GND	None
<b>HP Part # &amp; Options</b>					
Commercial	4N55*	HCPL-5500	HCPL-5530	HCPL-6550	HCPL-6530
MIL-PRF-38534, Class H	4N55/883B	HCPL-5501	HCPL-5531	HCPL-6551	HCPL-6531
MIL-PRF-38534, Class K	HCPL-257K	HCPL-550K	HCPL-553K	HCPL-655K	HCPL-653K
Standard Lead Finish	Gold Plate	Gold Plate	Gold Plate	Gold Plate	Solder Pads
Solder Dipped	Option #200	Option #200	Option #200		
Butt Cut/Gold Plate	Option #100	Option #100	Option #100		
Gull Wing/Soldered	Option #300	Option #300	Option #300		
<b>Class H SMD Part #</b>					
Prescript for all below	5962-	5962-	5962-	5962-	5962-
Either Gold or Solder	8767901EX	9085401HPX	8767902PX	8767904FX	87679032X
Gold Plate	8767901EC	9085401HPC	8767902PC	8767904FC	
Solder Dipped	8767901EA	9085401HPA	8767902PA		87679032A
Butt Cut/Gold Plate	8767901UC	9085401HYC	8767902YC		
Butt Cut/Soldered	8767901UA	9085401HYA	8767902YA		
Gull Wing/Soldered	8767901TA	9085401HXA	8767902XA		
Prescript for all below	5962-	5962-	5962-	5962-	5962-
Either Gold or Solder	8767905KEX	9085401KPX	8767906KPX	8767908KFX	8767907K2X
Gold Plate	8767905KEC	9085401KPC	8767906KPC	8767908KFC	
Solder Dipped	8767905KEA	9085401KPA	8767906KPA		8767907K2A
Butt Cut/Gold Plate	8767905KUC	9085401KYC	8767906KYC		
Butt Cut/Soldered	8767905KUA	9085401KYA	8767906KYA		
Gull Wing/Soldered	8767905KTA	9085401KXA	8767906KXA		

\*JEDEC registered part.

### 8 Pin Ceramic DIP Single Channel Schematic



Note base pin 7.

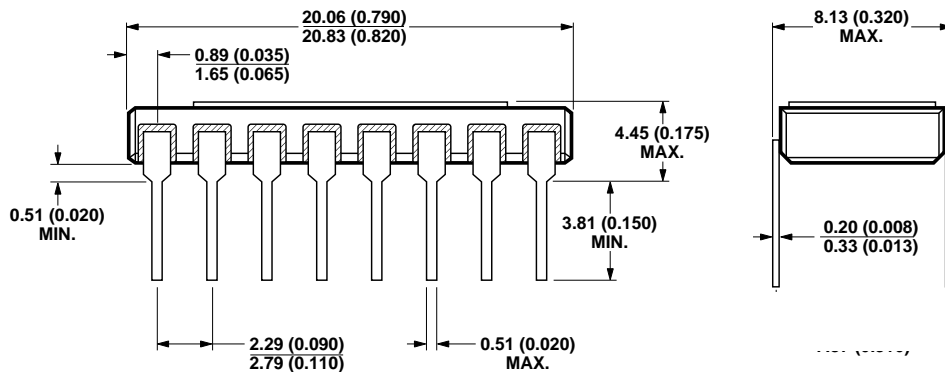
### Functional Diagrams

16 Pin DIP Through Hole 2 Channels	8 Pin DIP Through Hole 1 Channel	8 Pin DIP Through Hole 2 Channels	16 Pin Flat Pack Unformed Leads 4 Channels	20 Pad LCCC Surface Mount 2 Channels

**Note:** 8 pin DIP and flat pack devices have common  $V_{CC}$  and ground. 16 pin DIP and LCCC (leadless ceramic chip carrier) packages have isolated channels with separate  $V_{CC}$  and ground connections.

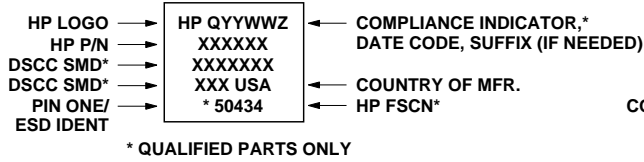
### Outline Drawings

16 Pin DIP Through Hole, 2 Channels

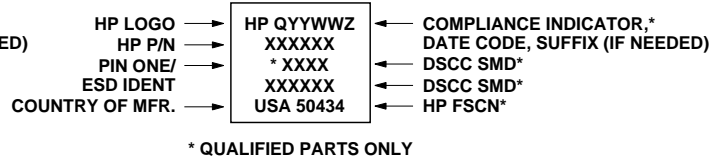


NOTE: DIMENSIONS IN MILLIMETERS (INCHES).

### Leaded Device Marking

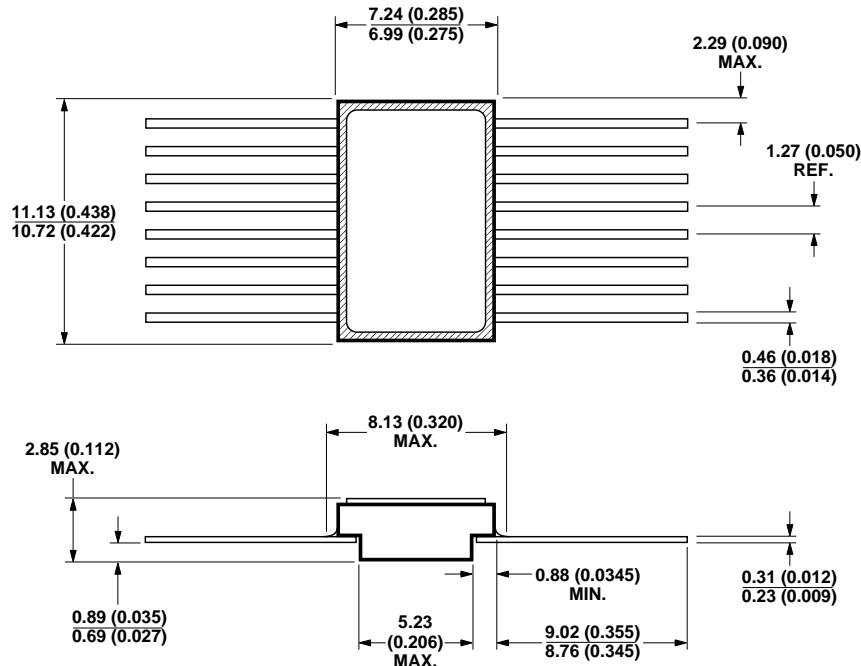


### Leadless Device Marking



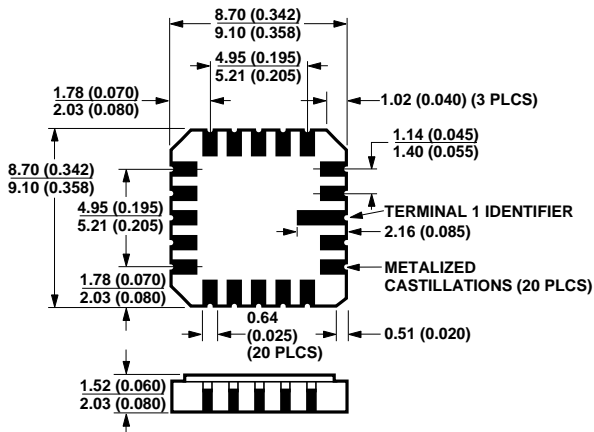
### Outline Drawings

#### 16 Pin Flat Pack, 4 Channels



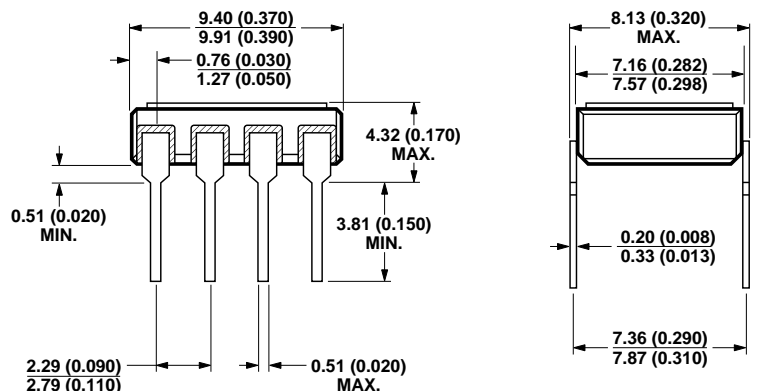
NOTE: DIMENSIONS IN MILLIMETERS (INCHES).

#### 20 Terminal LCCC Surface Mount, 2 Channels



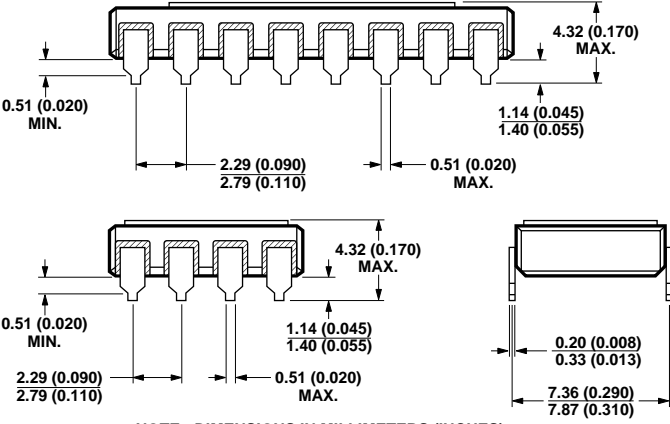
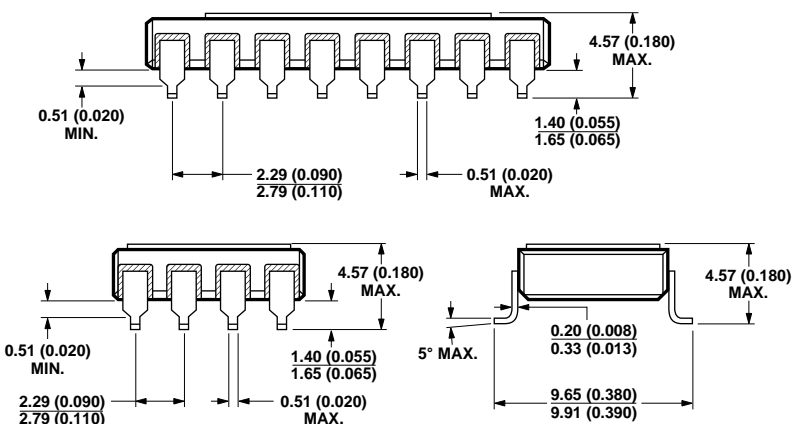
NOTE: DIMENSIONS IN MILLIMETERS (INCHES).  
SOLDER THICKNESS 0.127 (0.005) MAX.

#### 8 Pin DIP Through Hole, 1 and 2 Channel



NOTE: DIMENSIONS IN MILLIMETERS (INCHES).

## Hermetic Optocoupler Options

Option	Description
100	<p>Surface mountable hermetic optocoupler with leads trimmed for butt joint assembly. This option is available on commercial and hi-rel product in 8 and 16 pin DIP (see drawings below for details).</p>  <p>NOTE: DIMENSIONS IN MILLIMETERS (INCHES).</p>
200	<p>Lead finish is solder dipped rather than gold plated. This option is available on commercial and hi-rel product in 8 and 16 pin DIP. DSCC drawing part numbers contain provisions for lead finish. All leadless chip carrier devices are delivered with solder dipped terminals as a standard feature.</p>
300	<p>Surface mountable hermetic optocoupler with leads cut and bent for gull wing assembly. This option is available on commercial and hi-rel product in 8 and 16 pin DIP (see drawings below for details). This option has solder dipped leads.</p>  <p>NOTE: DIMENSIONS IN MILLIMETERS (INCHES).</p>

## Absolute Maximum Ratings

(No derating required up to +125°C)

Storage Temperature Range, $T_S$ .....	-65°C to +150°C
Operating Temperature, $T_A$ .....	-55°C to +125°C
Case Temperature, $T_C$ .....	+170°C
Junction Temperature, $T_J$ .....	+175°C
Lead Solder Temperature .....	260°C for 10 s
Peak Forward Input Current, (each channel, ≤ 1 ms duration), $I_{F PK}$ .....	40 mA
Average Input Forward Current, $I_{F AVG}$ (each channel) .....	20 mA
Reverse Input Voltage, $BV_R$ .....	See Electrical Characteristics
Average Output Current, $I_O$ (each channel) .....	8 mA
Peak Output Current, $I_O$ (each channel) .....	16 mA
Supply Voltage, $V_{CC}$ .....	-0.5 V to 20 V
Output Voltage, $V_O$ (each channel) .....	-0.5 V to 20 V
Input Power Dissipation (each channel) .....	36 mW
Output Power Dissipation (each channel) .....	50 mW
Package Power Dissipation, $P_D$ (each channel) .....	200 mW

## Single Channel 8 Pin, Dual Channel 16 Pin, and LCCC Only

Emitter Base Reverse Voltage, $V_{EBO}$ .....	3.0 V
Base Current, $I_B$ (each channel) .....	5 mA

## ESD Classification

(MIL-STD-883, Method 3015)

4N55, 4N55/883B, HCPL-257K, HCPL-5500/01/0K, and

HCPL-6530/31/3K .....

HCPL-5530/31/3K, HCPL-6550/51/5K .....

## Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Units
Input Current, Low Level	$I_{FL}$		250	μA
Input Current, High Level	$I_{FH}$	12	20	mA
Supply Voltage, Output	$V_{CC}$	2	18	V

**Electrical Characteristics** ( $T_A = -55^\circ\text{C}$  to  $+125^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Group A <sup>[12]</sup> Sub-groups	Limits			Units	Fig.	Note
				Min.	Typ.**	Max.			
Current Transfer Ratio	CTR*	$V_O = 0.4\text{ V}$ , $I_F = 16\text{ mA}$ , $V_{CC} = 4.5\text{ V}$	1, 2, 3	9	20		%	2, 3	1, 2, 10
Logic High Output Current	$I_{OH}$	$I_F = 0$ , $I_{F(\text{other channels})} = 20\text{ mA}$ , $V_O = V_{CC} = 18\text{ V}$	1, 2, 3		5	100	$\mu\text{A}$	4	1
Output Leakage Current	$I_{OLeak}^*$	$I_F = 250\text{ }\mu\text{A}$ , $I_{F(\text{other channels})} = 20\text{ mA}$ , $V_O = V_{CC} = 18\text{ V}$	1, 2, 3		30	250	$\mu\text{A}$	4	1
Input-Output Insulation Leakage Current	$I_{LO}^*$	$V_{LO} = 1500\text{ Vdc}$ , RH = 45% $T_A = 25^\circ\text{C}$ , $t = 5\text{ s}$	1			1.0	$\mu\text{A}$		3, 9
Input Forward Voltage	$V_F^*$	$I_F = 20\text{ mA}$	1, 2, 3		1.55	1.8 1.9	V	1	1, 14 1, 13
Reverse Breakdown Voltage	$BV_R^*$	$I_R = 10\text{ }\mu\text{A}$	1, 2, 3	5 3			V		1, 14 1, 13
Logic High Supply Current	Single Channel	$I_{CCH}^*$ $V_{CC} = 18\text{ V}$ , $I_F = 0\text{ mA}$	1, 2, 3		0.1	10	$\mu\text{A}$		1
	Dual Channel				0.2	20			1, 4
	Quad Channel				0.4	40			1
Logic Low Supply Current	Single Channel	$I_{CCL}^*$ $V_{CC} = 18\text{ V}$ , $I_F = 20\text{ mA}$	1, 2, 3		35	200	$\mu\text{A}$	5	1
	Dual Channel				70	400			1, 4
	Quad Channel				140	800			1
Propagation Delay Time to Logic High at Output	$t_{PLH}^*$	$R_L = 8.2\text{ k}\Omega$ , $C_L = 50\text{ pF}$ , $I_F = 16\text{ mA}$ , $V_{CC} = 5\text{ V}$	9, 10, 11		1.0	6.0	$\mu\text{s}$	6, 9	1, 6
Propagation Delay Time to Logic Low at Output	$t_{PHL}^*$				0.4	2.0			

\*For JEDEC registered parts.

\*\*All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

**Typical Characteristics,  $T_A = 25^\circ\text{C}$ ,  $V_{CC} = 5\text{ V}$** 

Parameter	Symbol	Typ.	Units	Test Conditions	Fig.	Note
Input Capacitance	$C_{IN}$	60	pF	$V_F = 0\text{ V}$ , $f = 1\text{ MHz}$		1
Input Diode Temperature Coefficient	$\frac{\Delta V_F}{\Delta T_A}$	-1.5	mV/°C	$I_F = 20\text{ mA}$		1
Resistance (Input-Output)	$R_{I-O}$	$10^{12}$	$\Omega$	$V_{I-O} = 500\text{ V}$		3
Capacitance (Input-Output)	$C_{I-O}$	1.0	pF	$f = 1\text{ MHz}$		1, 11
Transistor DC Current Gain	$h_{FE}$	250	-	$V_O = 5\text{ V}$ , $I_O = 3\text{ mA}$		1
Small Signal Current Transfer Ratio	$\frac{\Delta I_O}{\Delta I_F}$	21	%	$V_{CC} = 5\text{ V}$ , $V_O = 2\text{ V}$	7	1
Common Mode Transient Immunity at Logic High Level Output	$ CM_H $	1000	V/ $\mu\text{s}$	$I_F = 0\text{ mA}$ , $R_L = 8.2\text{ k}\Omega$ , $V_O(\text{min}) = 2.0\text{ V}$ $V_{CM} = 10\text{ V}_{P-P}$	10	1, 7
Common Mode Transient Immunity at Logic Low Level Output	$ CM_L $	-1000	V/ $\mu\text{s}$	$I_F = 16\text{ mA}$ , $R_L = 8.2\text{ k}\Omega$ , $V_O(\text{max}) = 0.8\text{ V}$ $V_{CM} = 10\text{ V}_{P-P}$	10	1, 7
Bandwidth	BW	9	MHz		8	8

**Multi-Channel Product Only**

Input-Input Insulation Leakage Current	$I_{I-I}$	1	pA	Relative Humidity = 45% $V_{I-I} = 500\text{ V}$ , $t = 5\text{ s}$		5, 9
Resistance (Input-Input)	$R_{I-I}$	$10^{12}$	$\Omega$	$V_{I-I} = 500\text{ V}$		5
Capacitance (Input-Input)	$C_{I-I}$	0.8	pF	$f = 1\text{ MHz}$		5

**Notes:**

- Each channel of a multi-channel device.
- Current Transfer Ratio is defined as the ratio of output collector current,  $I_O$ , to the forward LED input current,  $I_F$ , times 100%. CTR is known to degrade slightly over the unit's lifetime as a function of input current, temperature, signal duty cycle, and system on time. Refer to Application Note 1002 for more detail. In short, it is recommended that designers allow at least 20-25% guardband for CTR degradation.
- All devices are considered two-terminal devices; measured between all input leads or terminals shorted together and all output leads or terminals shorted together.
- The 4N55, 4N55/883B, HCPL-257K, HCPL-6530, HCPL-6531, and HCPL-653K dual channel parts function as two independent single channel units. Use the single channel parameter limits.  $I_F = 0\text{ mA}$  for channel under test and  $I_F = 20\text{ mA}$  for other channels.
- Measured between adjacent input pairs shorted together for each multichannel device.
- $t_{PHL}$  propagation delay is measured from the 50% point on the leading edge of the input pulse to the 1.5 V point on the leading edge of the output pulse. The  $t_{PLH}$  propagation delay is measured from the 50% point on the trailing edge of the input pulse to the 1.5 V point on the trailing edge of the output pulse.
- $CM_L$  is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state ( $V_O < 0.8\text{ V}$ ).  $CM_H$  is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state ( $V_O > 2.0\text{ V}$ ).
- Bandwidth is the frequency at which the ac output voltage is 3 dB below the low frequency asymptote. For the HCPL-5530 the typical bandwidth is 2 MHz.
- This is a momentary withstand test, not an operating condition.
- Higher CTR minimums are available to support special applications.
- Measured between each input pair shorted together and all output connections for that channel shorted together.
- Standard parts receive 100% testing at 25°C (Subgroups 1 and 9). SMD and 883B parts receive 100% testing at 25, 125, and -55°C (Subgroups 1 and 9, 2 and 10, 3 and 11, respectively).
- Not required for 4N55, 4N55/883B, HCPL-257K, 5962-8767901, and 5962-8767905 types.
- Required for 4N55, 4N55/883B, HCPL-257K, 5962-8767901, and 5962-8767905 types only.



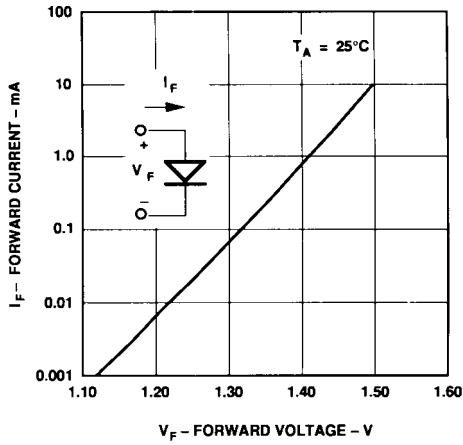


Figure 1. Input Diode Forward Current vs. Forward Voltage.

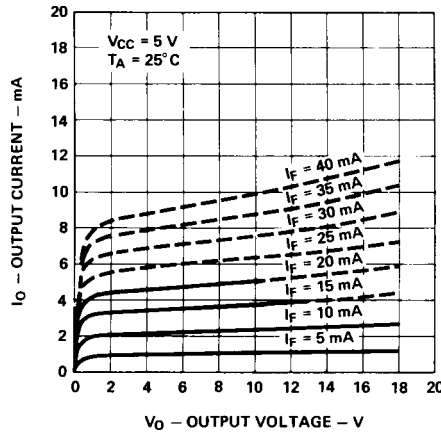


Figure 2. DC and Pulsed Transfer Characteristic.

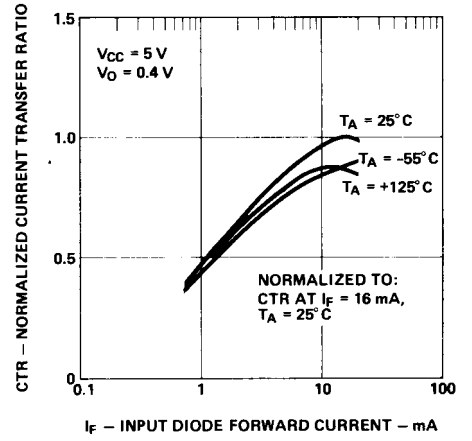


Figure 3. Normalized Current Transfer Ratio vs. Input Diode Forward Current.

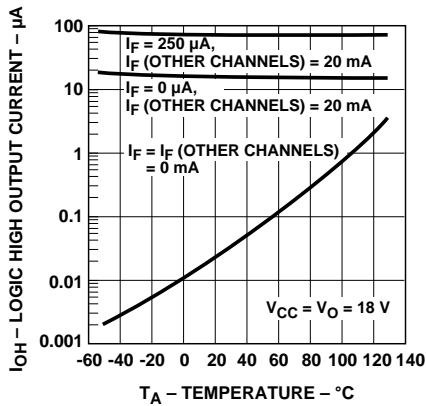


Figure 4. Logic High Output Current vs. Temperature.

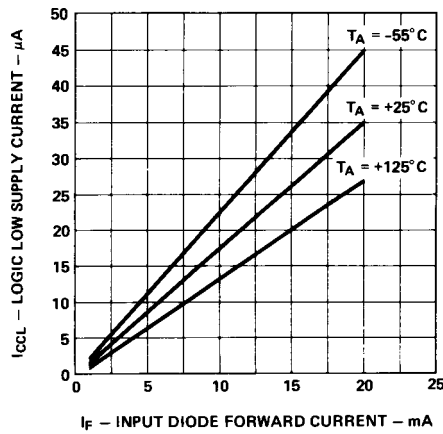


Figure 5. Logic Low Supply Current vs. Input Diode Forward Current.

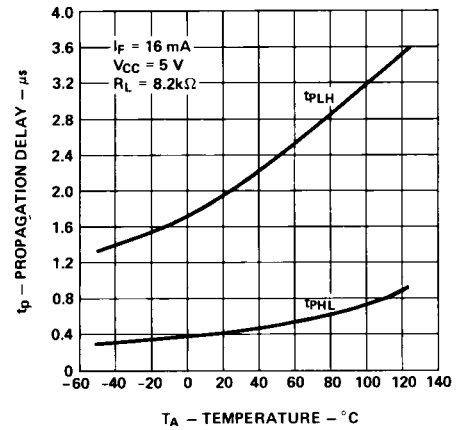


Figure 6. Propagation Delay vs. Temperature.

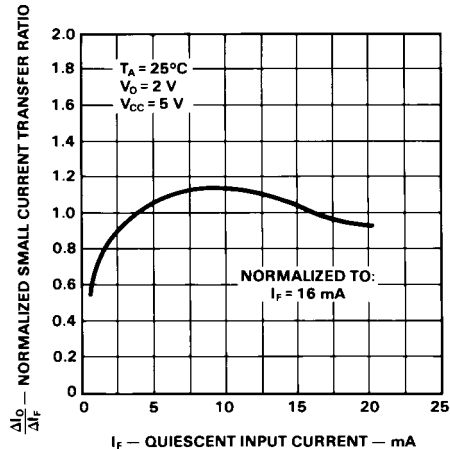


Figure 7. Normalized Small Signal Current Transfer Ratio vs. Quiescent Input Current.

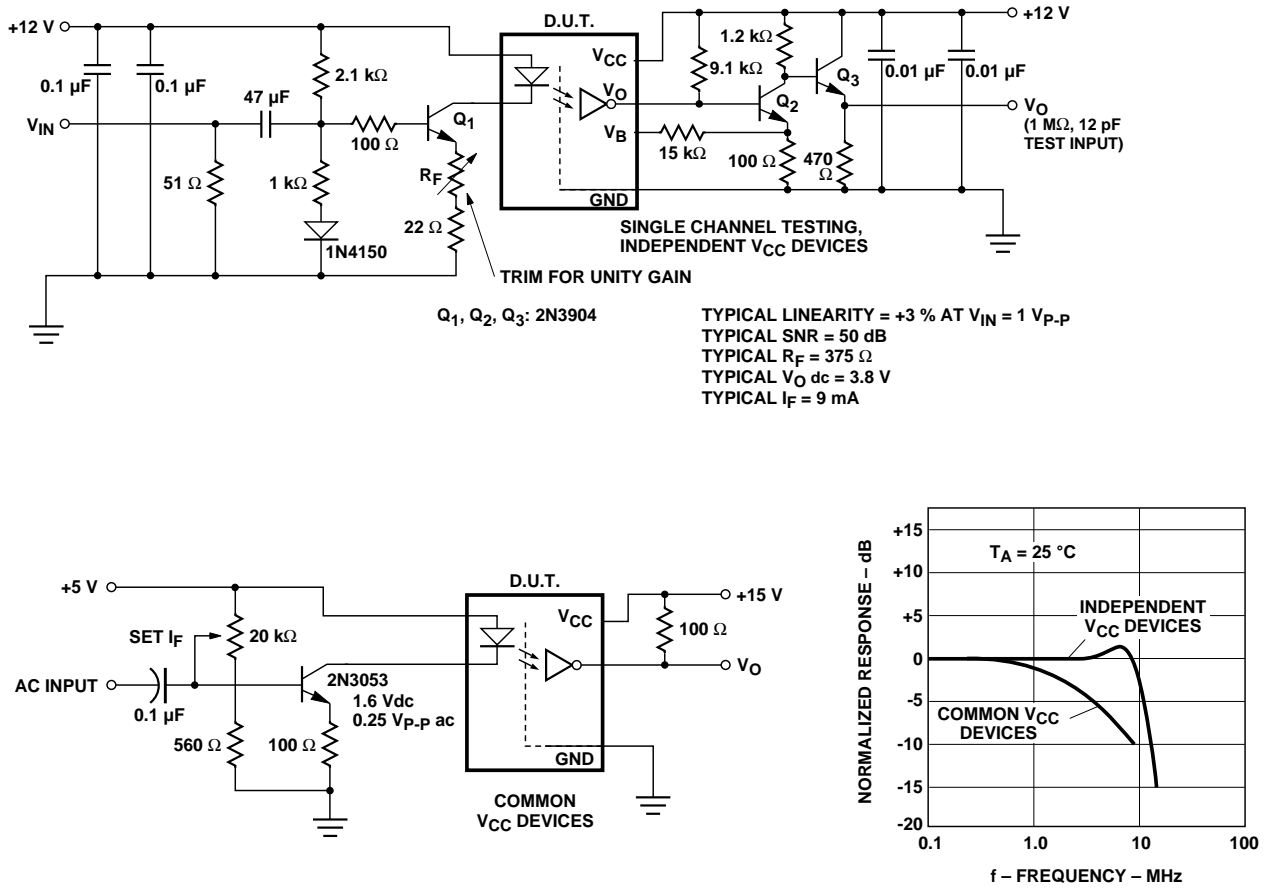


Figure 8. Frequency Response.

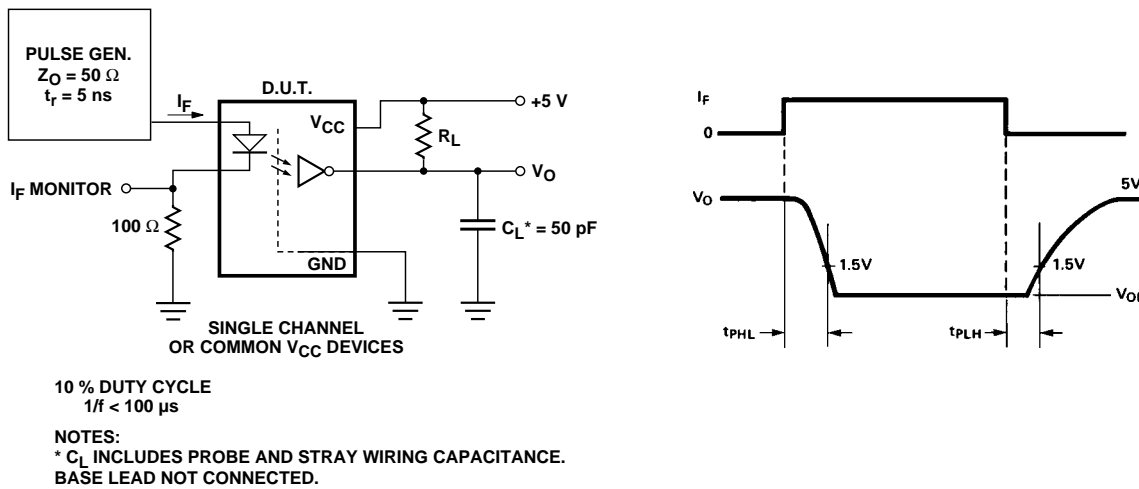


Figure 9. Switching Test Circuit.\*

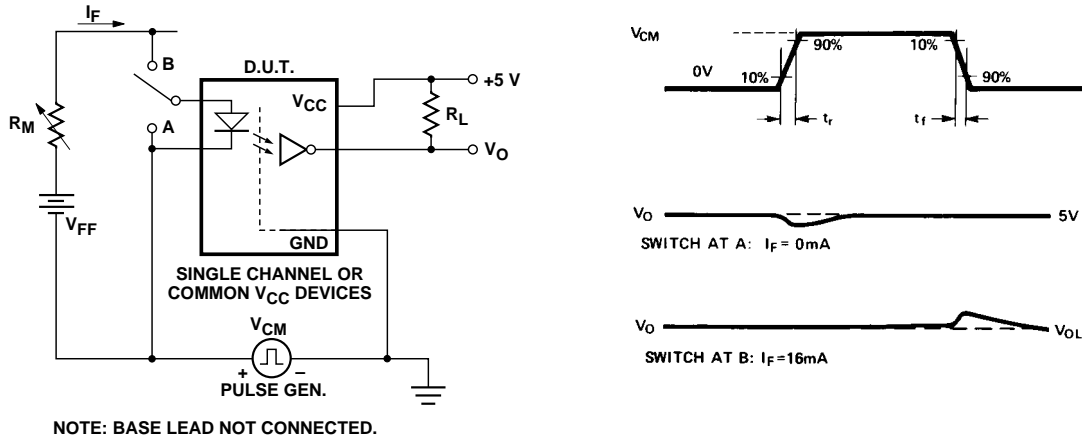
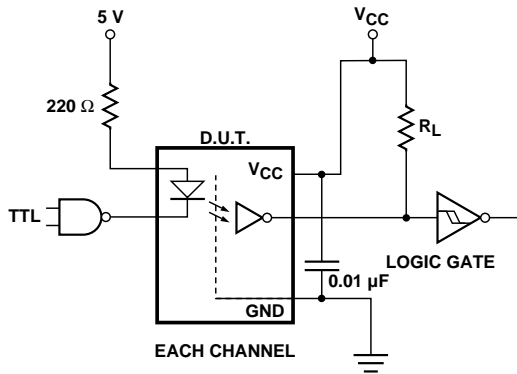


Figure 10. Test Circuit for Transient Immunity and Typical Waveforms.



Logic Family	LSTTL	CMOS	
Device No.	54LS14	CD40106BM	
V <sub>CC</sub>	5 V	5 V	15 V
R <sub>L</sub> 5% Tolerance	18 kΩ*	8.2 kΩ	22 kΩ

\*The equivalent output load resistance is affected by the LSTTL input current and is approximately 8.2 kΩ. This is a worst case design which takes into account 25% degradation of CTR. See App. Note 1002 to assess actual degradation and lifetime.

Figure 11. Recommended Logic Interface.

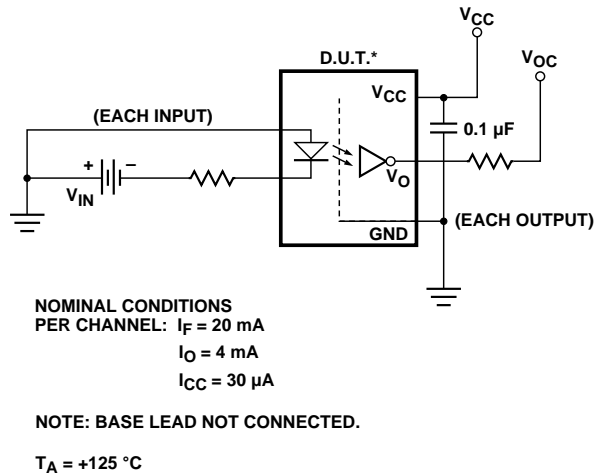


Figure 12. Operating Circuit for Burn-In and Steady State Life Tests. All Channels Tested Simultaneously.

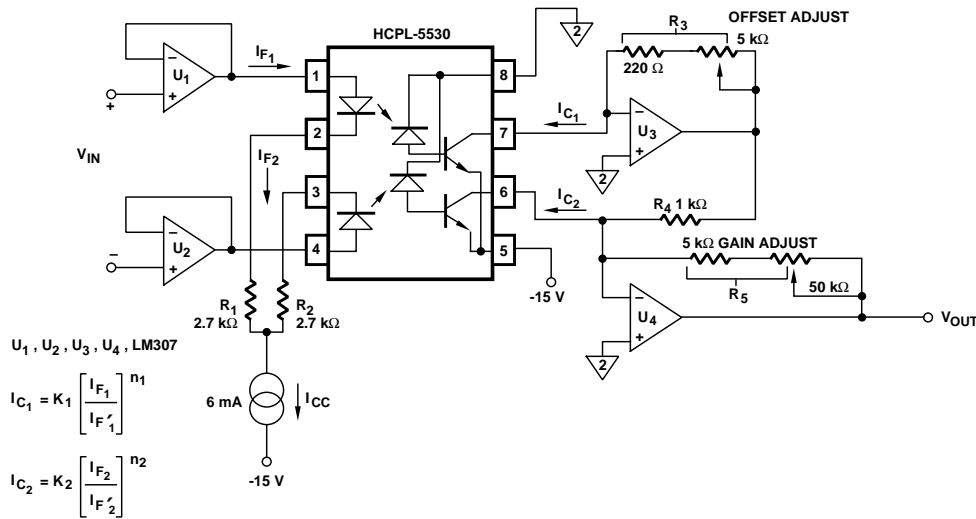


Figure 13. Isolation Amplifier Application Circuit.

### Description

The schematic uses a dual-channel, high-speed optocoupler (HCPL-5530) to function as a servo type dc isolation amplifier. This circuit operates on the principle that two optocouplers will track each other if their gain changes by the same amount over a specific operating region.

### Performance of Circuit

- 1% linearity for 10 V peak-to-peak dynamic range
- Gain drift: -0.03%/°C
- Offset Drift: ± 1 mV/°C
- 25 kHz bandwidth (limited by Op-Amps U1, U2)

### MIL-PRF-38534 Class H, Class K, and DSCC SMD Test Program

Hewlett-Packard's Hi-Rel Optocouplers are in compliance with MIL-PRF-38534 Classes H and K. Class H and Class K devices are also in compliance with DSCC drawings 5962-87679, and 5962-90854.

Testing consists of 100% screening and quality conformance inspection to MIL-PRF-38534.

[www.hp.com/go/isolator](http://www.hp.com/go/isolator)

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